



(0.80 mm) .0315"

HSEC8-130-01-S-D-EM2

HSEC8-140-01-L-D-EM2

HSEC8-EM SERIES

EDGE MOUNT EDGE RATE® CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-EM

Insulator Material:
Liquid Crystal Polymer

Contact:

BeCu

Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

Operating Temp:

-55 °C to +125 °C

Lead-Free Solderable:

Yes

RoHS Compliant:

Yes

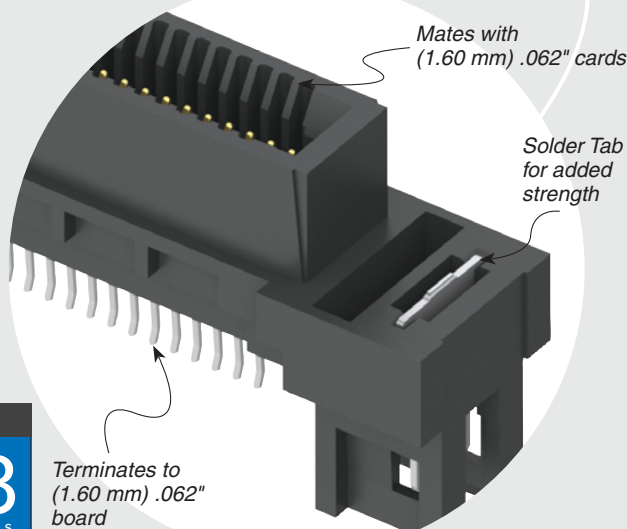
Card Mates:

(1.60 mm) .062" thick card,
HSC8

Cable Mates:

ECDP

EDGE
RATE
CONTACT



HIGH-SPEED CHANNEL PERFORMANCE

HSEC8-EM

Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com
or contact SIG@samtec.com

28
Gbps

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Other platings

HSEC8

1

POSITIONS
PER ROW

01

PLATING
OPTION

D

EM2

10, 20, 30, 40, 50, 60

POSITIONS PER ROW	A	B
40	(18.90) .744	(36.60) 1.441
50	(22.90) .902	(44.60) 1.756
60	(26.90) 1.059	(52.60) 2.071

-L

= 10 μ" (0.25 μm) Gold on contact,
Matte Tin on tail

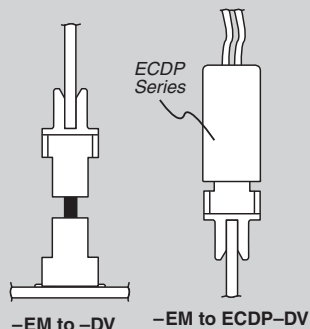
-S

= 30 μ" (0.76 μm) Gold on contact,
Matte Tin on tail

-EM2

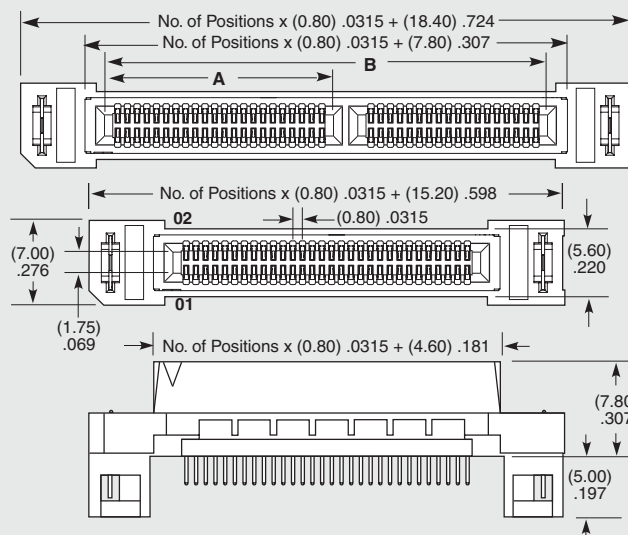
= (1.60 mm) .062"
thick PCB

APPLICATIONS



Note:

While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications.



OTHER SOLUTIONS

Polarized mates for
ECDP Series twinax cables

CONNECTOR	CABLE
HSEC8-113	ECDP-08
HSEC8-125	ECDP-16
HSEC8-137	ECDP-24
HSEC8-149	ECDP-32

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.